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CARDXX BOLSTERS BOARD OF DIRECTORS AND COMMENCES SEARCH FOR CEO

Englewood, Colorado - CardXX, Inc. (CXCQ.PK), a leading smartcard manufacturer, today announced that it has bolstered its Board of Directors and that Paul Lewis will step down as President and CEO effective April 1, 2005.

"I have fully enjoyed serving CardXX as its President and CEO," stated Lewis. "Now that the company is stabilized and poised for significant growth, I will vacate this position in order to make room for an executive that can build upon our recent successes." Lewis will remain active on the board of directors.

CardXX also announces the appointment of Eric Hellige to the company's board of directors. Mr. Hellige is a partner with the law firm of Pryor Cashman Sherman and Flynn and brings significant experience in the area of general corporate law, specializing in public corporate finance, securities, mergers and acquisitions, and general corporate counseling. He also represents a number of major banks acting as indenture trustee in connection with public and private debt, project finance and asset-backed financings, workouts and default administration. "We are very pleased to have someone of Eric's caliber join the board," stated Phil Worack, Chairman.

CardXX has developed patented technologies to securely encapsulate electronics into Smart Cards and other portable devices or form factors. CardXX partnered with Spyryus to engineer the first smart card to receive certification from the National Institute of Standards and Technology (NIST) for Overall Level 3 compliance, including Physical Security with the Federal Information Processing Standard (FIPS) 140 – Security Requirements for Cryptographic Modules.

The CardXX process offers the following unique advantages:

- Injected thermoset polymer encapsulates and protects all electronic elements completely and securely
- Low-temperature and low-pressure process prevents damage to delicate electronics and improves manufacturing yield
- Superior heat resistance and chemical resistance protects against physical and chemical attacks
- Physical access to chip electronics is difficult to obtain without severe damage or destruction of chip